

Figure 1 The amounts of physical adsorptions according to partial pressures of (a) HF and (b) CH<sub>3</sub>OH.

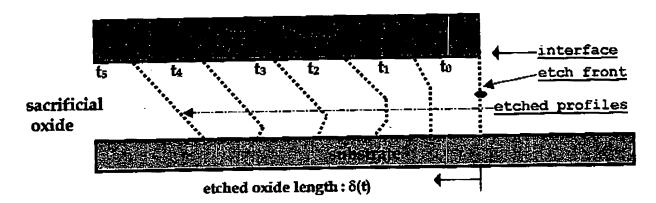


Figure 2. Schematic of etching mechanism to release microstructure.